

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method of manufacturing an electronic device, the electronic device comprising: a mount substrate having a patterned conductor exposed on one of surfaces of the mount substrate; and an electronic component having a connection electrode formed on one of surfaces of the electronic component, the one of the surfaces of the electronic component that has the connection electrode formed thereon being disposed to face toward the one of the surfaces of the mount substrate, the connection electrode being electrically connected and mechanically bonded to the patterned conductor of the mount substrate, the method comprising the steps of:

disposing the electronic component and the mount substrate such that the one of the surfaces of the electronic component faces toward the one of the surfaces of the mount substrate, and electrically connecting and mechanically bonding the connection electrode of the electronic component to the patterned conductor of the mount substrate;

placing a resin film over the electronic component and the mount substrate;

deforming the resin film by sucking a gas existing on an electronic-component side of the mount substrate from the other side of the mount substrate through a hole provided in the mount substrate, such that the resin film covers the electronic component and the mount substrate in close contact with a surface of the electronic component that is farther from the mount substrate and with a part of the one of the surfaces of the mount substrate, the part being located around the electronic component; and

adhering the resin film to the mount substrate by heating the resin film to cause the resin film to fluidize and thereafter to ~~harden~~, harden, wherein

the resin film is formed of a thermosetting resin; and

when the resin film hardens by being heated, the resin film contracts and thereby acts to push the electronic component toward the mount substrate.

2. (Currently Amended) A method of manufacturing an electronic device according to claim 1, wherein the resin film seals the ~~electronic equipment~~ electronic component.

3. (Original) A method of manufacturing an electronic device according to claim 1, wherein a cavity is formed between the one of the surfaces of the electronic component and the one of the surfaces of the mount substrate.

4. (Original) A method of manufacturing an electronic device according to claim 1, wherein the resin film is deformed with the resin film softened in the step of deforming the resin film.

5. (Original) A method of manufacturing an electronic device according to claim 1, wherein the hole formed in the mount substrate is disposed at a center portion of a region of the mount substrate where the electronic component is placed.

6. (Original) A method of manufacturing an electronic device according to claim 5, further comprising the step of closing the hole after the step of adhering the resin film.

7. (Original) A method of manufacturing an electronic device according to claim 1, wherein the hole formed in the mount substrate is disposed around a region of the mount substrate where the electronic component is placed, and the hole is closed with the resin film in the step of adhering the resin film.

8. (Original) A method of manufacturing an electronic device according to claim 1, wherein the hole formed in the mount substrate is a through hole for electrically connecting the patterned conductor disposed on the one of the surfaces of the mount substrate and another conductor provided in the mount substrate.

9. (Canceled)

10. (Currently Amended) A method of manufacturing an electronic device according to ~~claim 9~~, claim 1, wherein

the electronic component is a surface acoustic wave device and the electronic device is a band pass filter,

the method further comprises the step of determining in advance, based on results of measurement, a relationship between a processing condition employed in the step of adhering the resin film and the amount of change in a center frequency in a pass band of the band pass filter between before and after the step of adhering the resin film,

the processing condition includes at least one of a temperature of the resin film as heated and a period of time over which the resin film is ~~heated~~. heated, and

in the step of adhering the resin film, the processing condition is controlled so that a desired center frequency be obtained for the band pass filter, based on the relationship determined in advance.

11. (Currently Amended) A method of manufacturing an electronic device according to ~~claim 9~~, claim 1, wherein

the electronic component is a surface acoustic wave device and the electronic device is a band pass filter,

the method further comprises the step of determining in advance, based on results of measurement, a relationship between a processing condition employed in the step of adhering the resin film and the amount of change in a center frequency in a pass band of the band pass filter between before and after the step of adhering the resin film,

the resin film contains a hardening accelerator, and the processing condition includes a content of the hardening accelerator contained in the resin ~~film~~. film, and

in the step of adhering the resin film, the processing condition is controlled so that a desired center frequency be obtained for the band pass filter, based on the relationship determined in advance.